



Designing Sustainable Semiconductor Materials: Engineering the Future through Breakthrough Innovation and Strategic Collaboration

Semicon Europa, Munich | November 2024

DISCLAIMER

This document is provided by Soitec (the “Company”) for information purposes only.

The Company’s business operations and financial position are described in the Company’s Universal Registration Document (which notably includes the Annual Financial Report). The 2023-2024 Universal Registration Document will be filed with the French stock market authority (Autorité des Marchés Financiers, or AMF) on June 5, 2024. The French version of the 2023-2024 Universal Registration Document, together with English courtesy translation for information purposes, will be made available for consultation on the Company’s website (www.soitec.com), in the section Company - Investors - Financial Reports.

Your attention is drawn to the risk factors described in Chapter 2.1 (Risk factors and controls mechanism) of the Company’s Universal Registration Document.

This document contains summary information and should be read in conjunction with the Universal Registration Document.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company’s future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future. Forward-looking statements are not a guarantee of the Company’s future performance. The occurrence of any of the risks described in Chapter 2.1 (Risk factors and controls mechanism) of the Universal Registration Document may have an impact on these forward-looking statements. In particular, the future consequences of geopolitical conflicts, notably the

Ukraine / Russia situation, as well as rising inflation, may result in greater impacts than currently anticipated in these forward-looking statements.

Any market shares presented herein are based on internal estimates and relate to that share of the market segment served and addressed by Soitec which may exclude broader segments of the market and competing technologies.

The Company’s actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company’s financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward-looking statements contained in this document, such elements cannot be construed as a reliable indication of the Company’s future results or developments. The Company does

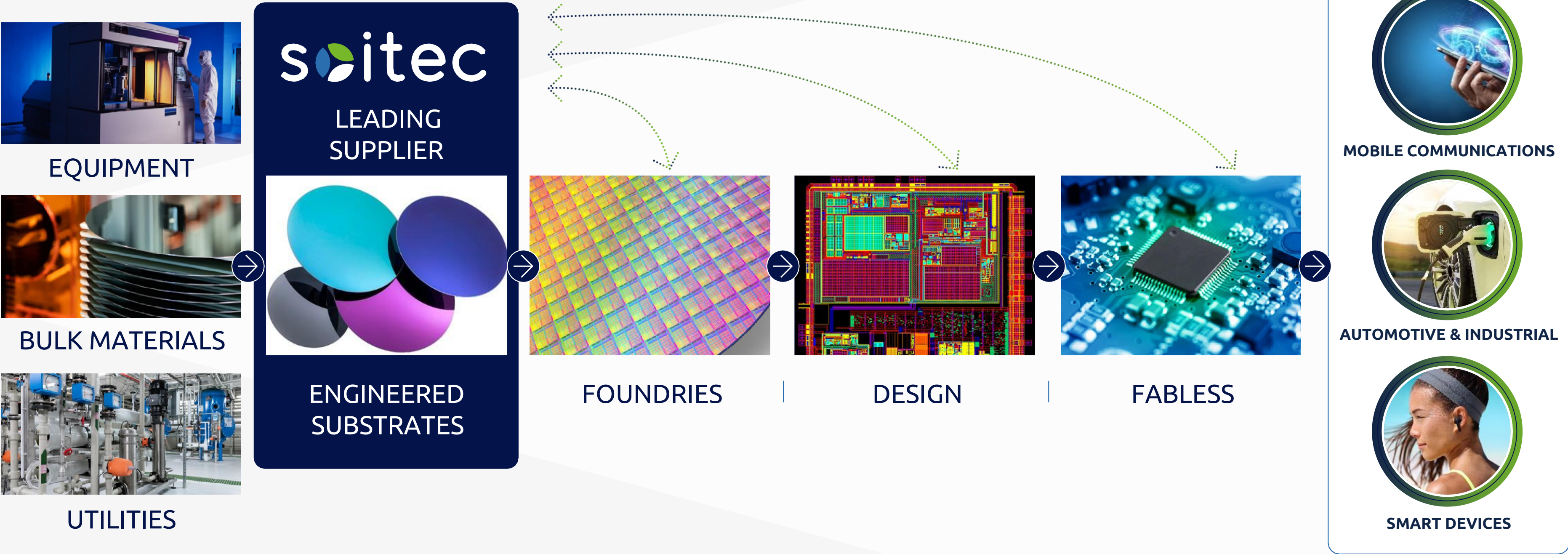
not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document.

This document does not constitute or form part of an offer or a solicitation to purchase, subscribe for, or sell the Company’s securities in any country whatsoever. This document, or any part thereof, shall not form the basis of, or be relied upon in connection with, any contract, commitment or investment decision.

Notably, this document does not constitute an offer or solicitation to purchase, subscribe for or to sell securities in the United States. Securities may not be offered or sold in the United States absent registration or an exemption from the registration under the U.S. Securities Act of 1933, as amended (the “Securities Act”). The Company’s shares have not been and will not be registered under the Securities Act.

Neither the Company nor any other person intends to conduct a public offering of the Company’s securities in the United States.

SOITEC HAS BUILT A UNIQUE POSITION IN THE VALUE CHAIN BUILDING CUSTOMER INTIMACY TO MAKE OUR PRODUCTS A STANDARD AND BECOME A REFERENCE



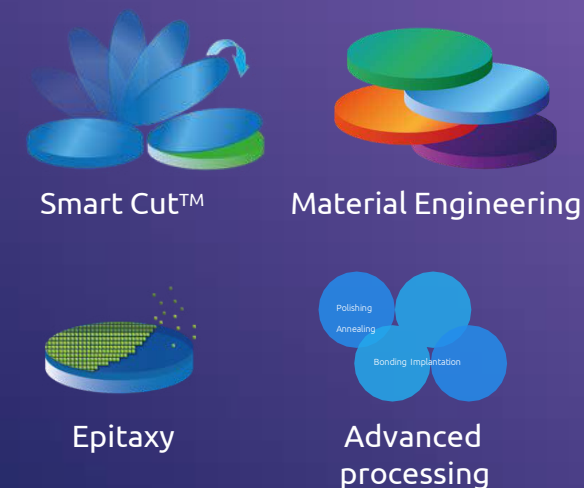
LEVERAGING MATERIALS SCIENCES

TO ENABLE UNIQUE APPLICATIONS

Leverage
MATERIALS
INTRINSIC
PROPERTIES

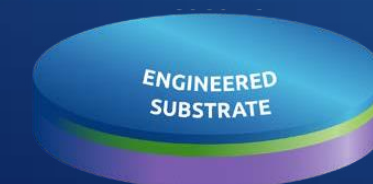


Develop
TECHNOLOGY
SOLUTIONS



Design
ENGINEERED
SUBSTRATES

- SOI product portfolio
- Anything-on-Anything (active layer on substrate)



Thin active layer
Functional /
insulating layer
Base wafer

Enable
NEW PROPERTIES,
ENHANCED PERFORMANCE,
IMPROVED ENERGY
CONSUMPTION

Connectivity

Low-power computing

Energy efficiency

Electric vehicles

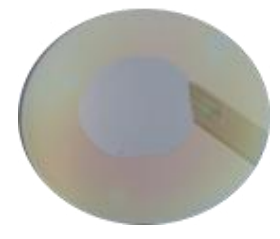
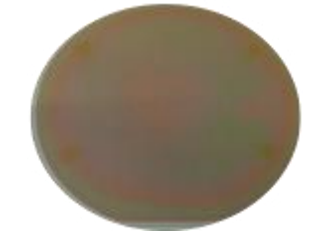
Quantum computing

3D integration

Data rate & bandwidth

ANYTHING-ON-ANYTHING - SOITEC INNOVATION DNA

BEST ACTIVE LAYER(S) ON FUNCTIONAL SUBSTRATE

		ACTIVE LAYER							
		Silicon	Piezo	SiC	InP	GaN	GaAs	Ge	Others
SUBSTRATE	Silicon or SOI								Diamond GaOx 2D materials
	Sapphire								
	SiC or polySiC								
	GaAs								
	Device wafer								

BUILDING A DIVERSE PRODUCT PORTFOLIO TO FUEL OUR DIVISIONS VALUE CREATION ACROSS 3 STRATEGIC END MARKETS



RF-SOI

FD-SOI

Power-SOI

Imager-SOI

Photonics-SOI

POI

SmartSiC™

RF-GaN

Power-GaN

SmartGaN

InP

New materials

PREPARING
EXPANSION
BEYOND

EXPANDING INTO
COMPOUND
SEMICONDUCTORS

STRENGTHENING
SOI LEADERSHIP

+ LICENSING / PATENT MONETIZATION

**TARGETING
MULTIPLE END
MARKETS**



**MORE PRODUCT
LINES
>\$100M**



DIVERSIFYING ON MULTIPLE FRONTS

**DIVERSIFIED
SUPPLIER
BASE**



DEVELOPING OUR GLOBAL MINDSET



**BROADER
CUSTOMER
BASE**



MULTIREGIONAL INNOVATION & MANUFACTURING FOOTPRINT

PARTNERSHIPS WITH LEADING INNOVATION PLATFORMS



Expanding our R&D depth while keeping compatibility with internal R&D corridors

Early prototyping, focus on lead time and quality

Accessing new ideas, disruptive process improvements, broader expertise



WE AIM TO BE AN ESG ROLE MODEL

CLIMATE

-37% by FY30

*Absolute scope 1 & 2
emissions vs CY20 baseline*



WATER

50% by FY30

*Total percentage of water
recycled and reused*



DIVERSITY

≥40% by FY30

*Women among Soitec
employees*



ETHICS

90% by FY26

*Employees having completed the
e-learning on the Code of Conduct*



THANK YOU

